

Gebräuchliche Abkürzungen für die Bauformbezeichnung elektronischer Bauelemente
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ASIC	Application Specific Integrated Circuit	P-QFP	Plastic Quad Flat Pack
C-Flat Pack	Ceramic Flat Pack	P-SO	Plastic Small Outline
C-LCC	Ceramic Leaded Chip Carrier	P-TSOP	Plastic Thin Small Outline Package
C-PGA	Ceramic Pin Grid Array	PCB	Printed Circuit Board
COB	Chip on Board	SIP	Single Inline Package
CSP	Chip Scale Package	SMD	Surface Mount Device
DIP	Dual Inline Package	SO	Small Outline
DRAM	Dynamic Random Access Memory	SOD	Small Outline Diode
EIAJ	Electronic Industries Association of Japan	SOJ	Small Outline J-Lead
FC	Flip Chip	SOT	Small Outline Transistor
FCIP	Flip Chip in Package	SSOP	Shrink Small Outline Package
FCOB	Flip Chip on Board	TAB	Tape Automated Bonding
FPC	Flexible Printed Circuit	TCE	Thermal Coefficient of Expansion
JEDEC	Joint Electronic Device Engineering Council	TCP	Tape Carrier Package
MSL	Moisture Sensitivity Level	THP	Through Hole Packaging
LB	Lead Bonding	THT	Through Hole Technology
LF	Leadframe	TO	Transistor Outline
MCM	Multi Chip Module	TSOP II	Thin Small Outline Package, Type II
µBGA	Mikro Ball Grid Array	UTSOP	Ultra Thin Small Outline Package
P-LCC	Plastic Leaded Chip Carrier	ZIP	Zigzag Inline Package